

## PATENT APPLICATION

In re application of:

Osamu Furukawa et al.

Atty. Docket No. 108066-00087

Serial No.: 10/615,298

Examiner:

Filed: July 9, 2003

Art Unit:

For: SURFACE-MOUNTED ELECTRONIC COMPONENT MODULE AND METHOD

FOR MANUFACTURING THE SAME.

## INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Date: September 8, 2005

Sir:

Pursuant to 37 CFR §1.56, the attention of the Patent and Trademark Office is hereby directed to the information item(s) listed on the attached Form PTO-SB08. Unless otherwise indicated herein, one copy of each item(s) is attached. respectfully requested that the information be expressly considered during the prosecution of this application, and that the item(s) be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

- This Information Disclosure Statement is being filed (a) within three months of the U.S. filing date, OR (b) before the mailing date of a first Office Action on the merits in the present application, OR (c) accompanies a Request for Continued Examination. No certification or fee is required.
- $\boxtimes$ This Information Disclosure Statement is being filed more than three months after the U.S. filing date AND after the mailing date of the first Office Action on the merits, but before the mailing date of a Final Rejection or Notice of Allowance.
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  - П I hereby certify that no item of information in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to my knowledge after making reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this Information Disclosure Statement. 37 CFR §1.97(e)(2).

 $\Box$ A check in the amount of \$180.00 in payment of the fee under 37 CFR §1.17(p). Please charge any fee deficiency or credit any overpayment to Deposit Account No. 01-2300 as needed to ensure consideration of the disclosed information. This Information Disclosure Statement is being filed more than three months after the U.S. filing date and after the mailing date of a Final Rejection or Notice of Allowance, but before payment of the Issue Fee. Applicant(s) hereby petition(s) that the Information Disclosure Statement be considered. Attached is our check in the amount of \$180.00 in payment of the petition fee under 37 CFR §1.17(i)(1). Please charge any fee deficiency or credit any overpayment to Deposit Account No. 01-2300 as needed to ensure consideration of the disclosed information. I hereby certify that each item of information contained in this Information Disclosure Statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement. 37 CFR §1.97(e)(1).  $\Box$ I hereby certify that no item of information in this Information b. Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to my knowledge after making reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this Information Disclosure Statement. 37 CFR §1.97(e)(2).  $\boxtimes$ 4. The references were cited in a counterpart foreign application. An English language version of the European search report is attached for the Examiner's information. English-language Abstracts of the non-English language references are

Respectfully submitted,

attached hereto. Copies of the U.S. Patent References are not enclosed in view of

the recent changes in the U.S. Patent rules effective October 21, 2004

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Enclosures: PTO/SB/08a&b, References (3), European Search Report

PTO/SB/08a (08-03)

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Form PTO/SB/08a

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|------------------------|-----------------------|--|--|--|
| Application Number     | 10/615,298            |  |  |  |
| Filing Date            | July 9, 2003          |  |  |  |
| First Named Inventor   | Osamu FURUKAWA et al. |  |  |  |
| Art Unit               |                       |  |  |  |
| Examiner Name          |                       |  |  |  |
| Attorney Docket Number | 108066-00087          |  |  |  |

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PTO/SB/08b (08-03)

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U.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE required to respond to a collection of information unless it contains a valid OMB control number. Under the Paperwork Reduction Act of Substitute for form 1449B/PTO Complete if Known **Application Number** 10/615,298 INFORMATION DISCLOSURE Filing Date July 9, 2003 STATEMENT BY APPLICANT First Named Inventor Osamu FURUKAWA et al. Form PTO/SB/08b Art Unit **Examiner Name** Sheet Attorney Docket Number 108066-00087

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| Examiner Initials*              | nitials* No.1 catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published. |   |          |  |  |  |
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